

# Preliminary Technical Information

# Power MOSFET TrenchHV™ HiPerFET™

# IXFH160N15T

N-Channel Enhancement Mode Avalanche Rated

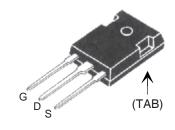


$V_{\rm DSS}$	=	150V
I <sub>D25</sub>	=	160A
R <sub>DS(on)</sub>	≤	9.6m $\Omega$

Symbol	Test Conditions	Maximum	Ratings	
V <sub>DSS</sub>	T <sub>1</sub> = 25°C to 175°C	150	V	
V <sub>DGR</sub>	$T_J^\circ = 25^\circ C$ to 175°C, $R_{GS} = 1M\Omega$	150	V	
V <sub>GSM</sub>	Transient	± 30	V	
I <sub>D25</sub>	T <sub>C</sub> = 25°C	160	Α	
ILRMS	Lead Current Limit, RMS	75	Α	
I <sub>DM</sub>	$T_{\rm C} = 25$ °C, pulse width limited by $T_{\rm JM}$	430	Α	
I <sub>A</sub>	T <sub>C</sub> = 25°C	5	A	
É <sub>AS</sub>	$T_{c} = 25^{\circ}C$	1	J	
dV/dt	$I_{S} \leq I_{DM}, V_{DD} \leq V_{DSS}, T_{J} \leq 175^{\circ}C$	10	V/ns	
$\overline{P_d}$	$T_{\rm C} = 25^{\circ}{\rm C}$	830	W	
$T_{\rm J}$		-55 +175	°C	
<b>T</b> JM		175	°C	
T <sub>stg</sub>		-55 +175	°C	
T,	1.6 mm (0.062 in.) from case for 10s	300	°C	
T <sub>SOLD</sub>	Plastic body for 10 seconds	260	°C	
M <sub>d</sub>	Mounting torque	1.13 / 10	Nm/lb.in.	
Weight		6	g	

Symbol (T <sub>J</sub> = 25°C t	Test Conditions unless otherwise specified)	Characte Min.	eristic ' Typ.		
BV <sub>DSS</sub>	$V_{GS} = 0V, I_{D} = 250\mu A$	150			V
V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 1mA$	2.5		5.0	V
I <sub>gss</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 200	nA
I <sub>DSS</sub>	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$ $T_{J} = 150^{\circ}C$			5 250	μ <b>Α</b> μ <b>Α</b>
R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 0.5 \bullet I_{D25}, Note 1$		8.0	9.6	mΩ

#### TO-247 (IXFH)



G = Gate	D = Drain			
S = Source	TAB = Drain			

#### **Features**

- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- easy to drive and to protect
- 175 °C Operating Temperature

### Advantages

- Easy to mount
- Space savings
- High power density

## **Applications**

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- AC motor control
- Uninterruptible power supplies
- High speed power switching applications



Symbol Test Conditions Chara		acteristic	: Values		
(T <sub>J</sub> = 25°C unless otherwise specified)		Min.	Тур.	Max.	
<b>g</b> <sub>fs</sub>		$V_{DS} = 10V, I_{D} = 60A, Note 1$	65	105	S
C <sub>iss</sub>	)			8800	pF
C <sub>oss</sub>	}	$V_{GS} = 0V, V_{DS} = 25V, f = 1 MHz$		1170	pF
C <sub>rss</sub>	J			150	pF
t <sub>d(on)</sub>	)	Resistive Switching Times		21	ns
t <sub>r</sub>		$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		21	ns
$\mathbf{t}_{d(off)}$	7			52	ns
t <sub>f</sub>	)	$R_{_{G}} = 2\Omega \text{ (External)}$		29	ns
Q <sub>g(on)</sub>	)			160	nC
$Q_{gs}$	}	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 25A$		43	nC
$\mathbf{Q}_{gd}$	J			46	nC
R <sub>thJC</sub>					0.18 °C/W
$R_{\scriptscriptstylethCS}$				0.25	°C/W

#### **TO-247AD Outline** 0 2 - Drain Terminals: 1 - Gate Tab - Drain 3 - Source Dim. Millimeter Inches Min. Max. Min. Max 4.7 .185 .209 5.3 2.2 2.54 .087 .102 A, 2.2 2.6 .059 .098 b 1.0 1.4 .040 .055 1.65 2.13 .065 .084 b, 2.87 .123 3.12 .113 $b_2$ С .031 .8 .016 D 20.80 21.46 .819 .845 F 15.75 16.26 .610 .640 0.205 0.225 е 5 20 5 72 L 19.81 20.32 .780 .800

4.50

3.65

6.40

5.49

ÆΡ

Q

R

S

3.55

5.89

4.32

6.15 BSC

.177

.144

.216

.140

.170

0.232 0.252

242 BSC

#### Source-Drain Diode

#### **Characteristic Values**

$(T_{J} = 25^{\circ}C, t)$	ınless otherwise specified)	Min.	Тур.	Max.	
I <sub>s</sub>	$V_{GS} = 0V$			160	Α
I <sub>SM</sub>	Repetitive, pulse width limited by $T_{JM}$			430	Α
V <sub>SD</sub>	$I_F = I_S$ , $V_{GS} = 0V$ , Note 1			1.2	V
t <sub>rr</sub>	1 - 804 di/dt - 2004/us		90	160	μs
Q <sub>RM</sub>	$I_F = 80A$ , -di/dt = 200A/ $\mu$ s $V_R = 75V$ , $V_{GS} = 0V$		12		Α
I <sub>RM</sub>	н / us		0.55		μС

Notes: 1. Pulse test,  $t \le 300\mu s$ ; duty cycle,  $d \le 2\%$ .

## PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

Fig. 1. Output Characteristics @ 25°C

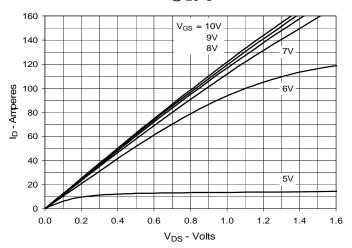


Fig. 3. Output Characteristics @ 150°C

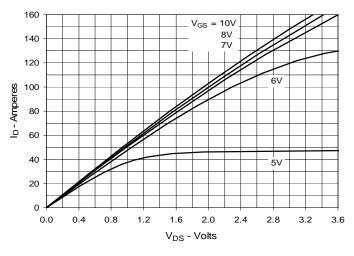


Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 80A$  Value vs. Drain Current

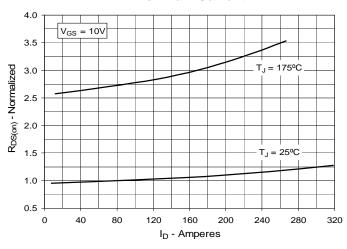


Fig. 2. Extended Output Characteristics @ 25°C

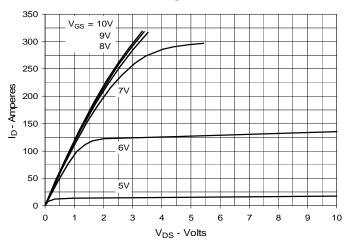


Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 80A$  Value vs. Junction Temperature

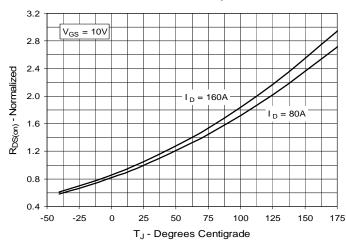
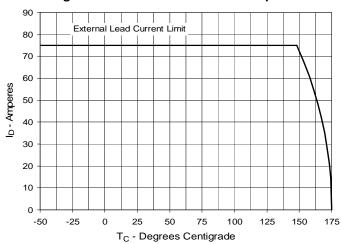


Fig. 6. Drain Current vs. Case Temperature





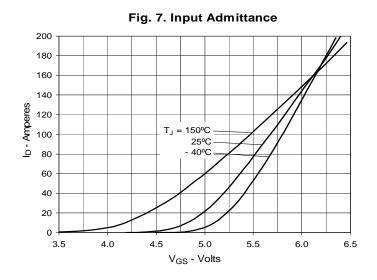
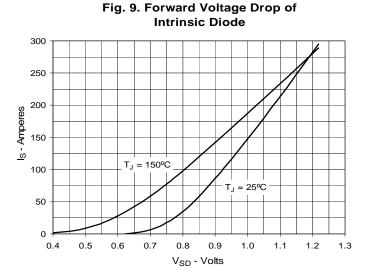
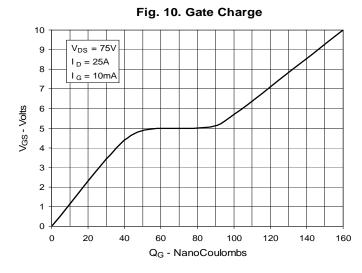
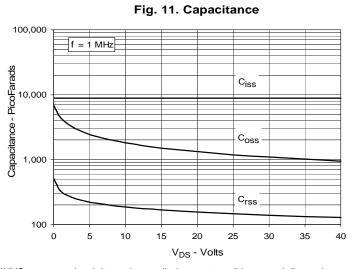
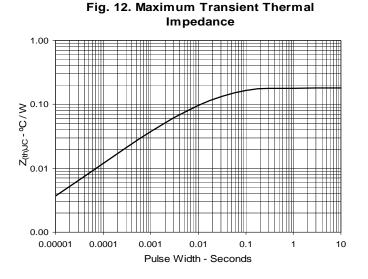


Fig. 8. Transconductance  $T_{J} = -40^{\circ}C$ 100 80 60 25°C 150°C I<sub>D</sub> - Amperes









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Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

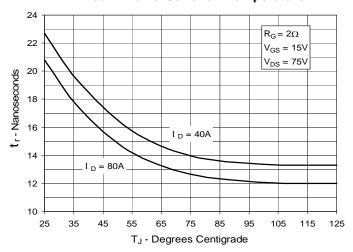


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

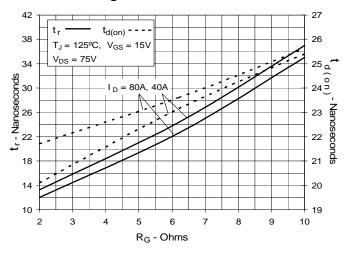


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

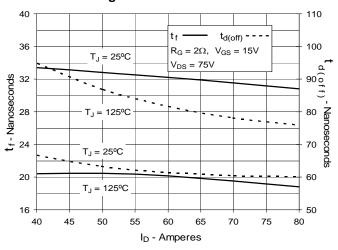


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

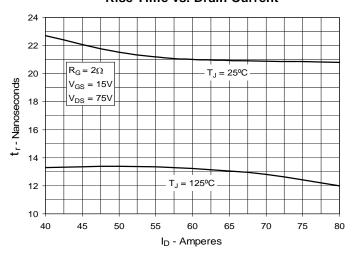


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

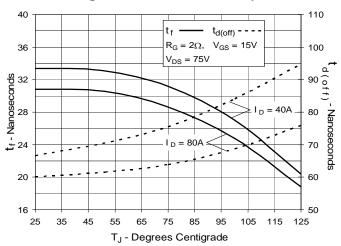


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

